

FLEX

7-8 November

Singapore

Southeast Asia 2019

Marina Bay Sands Convention Centre
Jasmine Ballroom | Level 3

Topics and Abstracts:

Speaker	Mr. Boon Keng LOK
Company	A*STAR - Singapore Institute of Manufacturing Technology (SIMTech)
Designation	Program Manager
Title of Presentation	Application Development of Flexible Hybrid Electronics for IoT Sensing Devices
Abstract	<p>This presentation will introduce and discuss the technology trend in application of IoT sensing devices for various markets such as human monitoring in healthcare and manufacturing, equipment health and manufacturing condition monitoring in Industry 4.0 and nutrient/environmental monitoring in precision agriculture, applicable markets in Singapore, concept and approach of Flexible Hybrid Electronics (FHE) to address the challenges for various IoT applications. The presentation will elaborate the application development of functional demonstrators using printed pressure array sensors and printed temperature sensors.</p>

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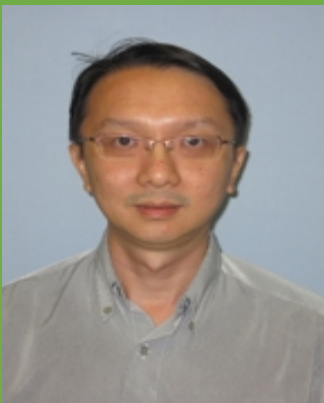
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Biography



Lok received his Master of Science (Management of Technology) and Bachelor of Science (Physics) from National University of Singapore. He has served the semiconductor and electronics industry for 10 years prior joining SIMTech in 2001 as the roles of process / product engineer to engineering manager in both MNC and SME settings under different cultural environment (Singapore, Japan, Malaysia).

In SIMTech, he has researched into advanced substrate and bumping technology, embedded passives, further explored into printing electronics with conventional graphic printing technology such as screen, flexographic and inkjet printing. Currently he is the Programme Manager of Large Area Processing Programme and is responsible to define and develop the strategic research platform for LAP. He is concurrently holding the Team Lead position of Application Technology Team to develop applications of flexible hybrid printed electronics and printed functional films based on hybrid Roll-to-Roll manufacturing technology.